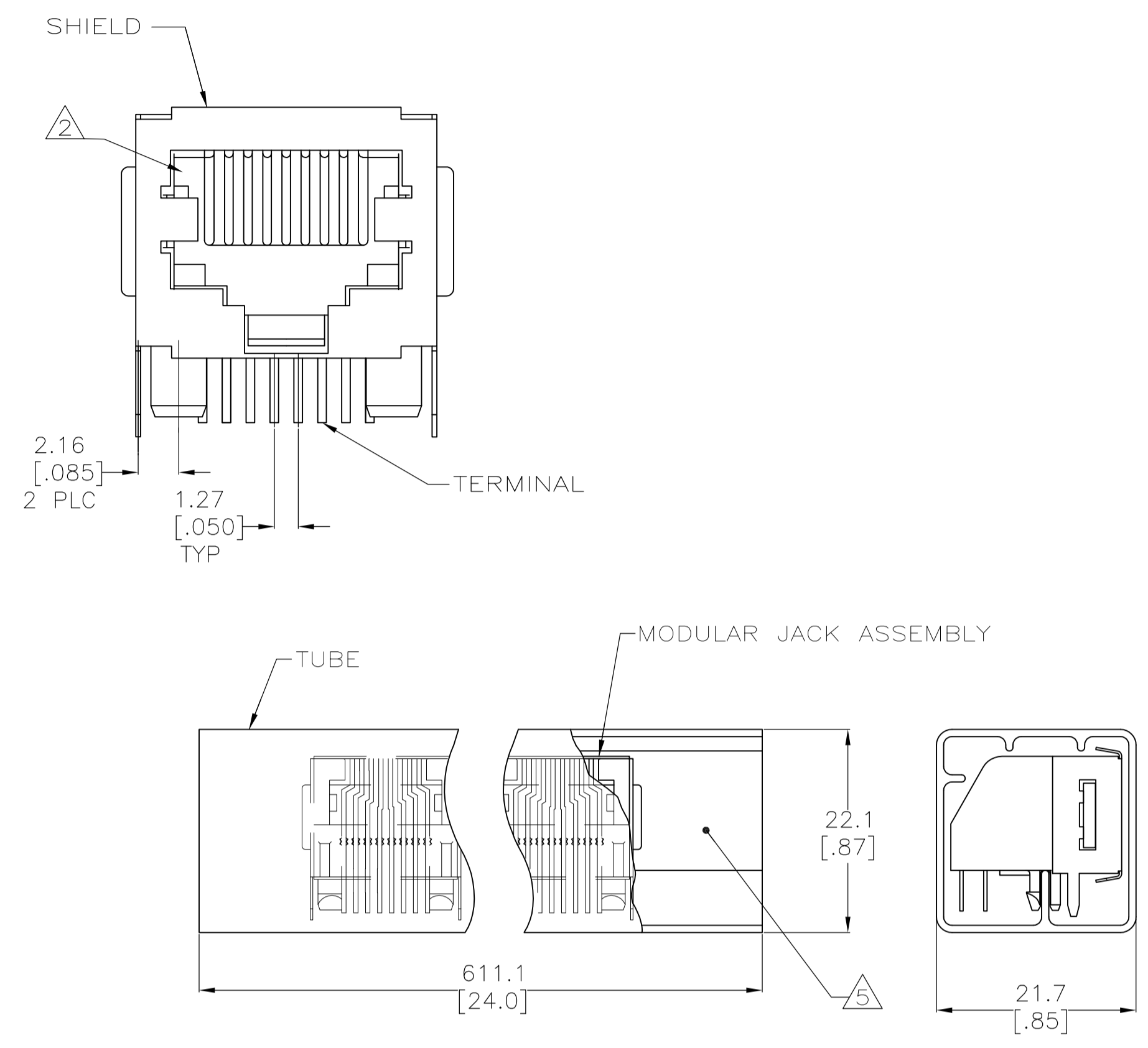
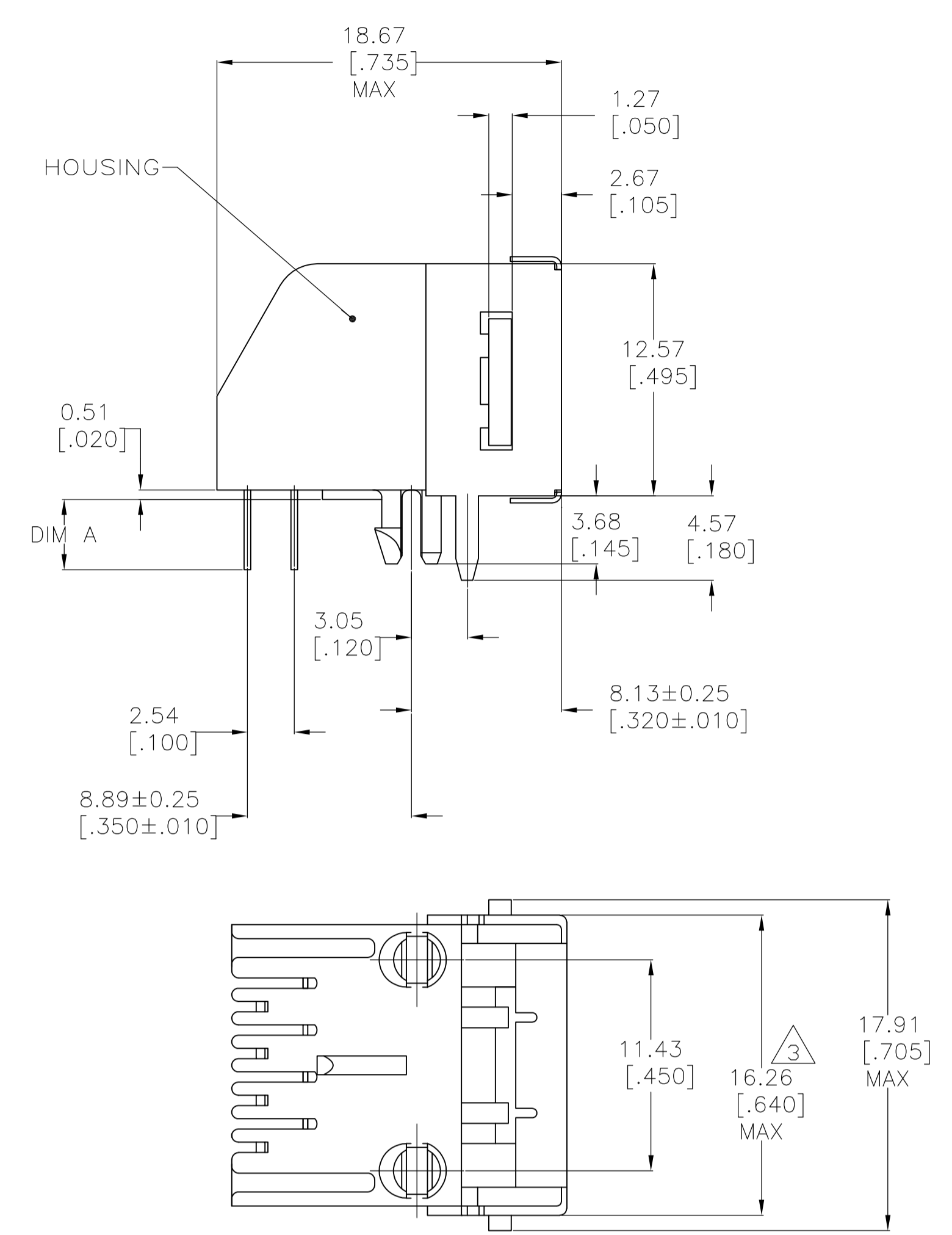
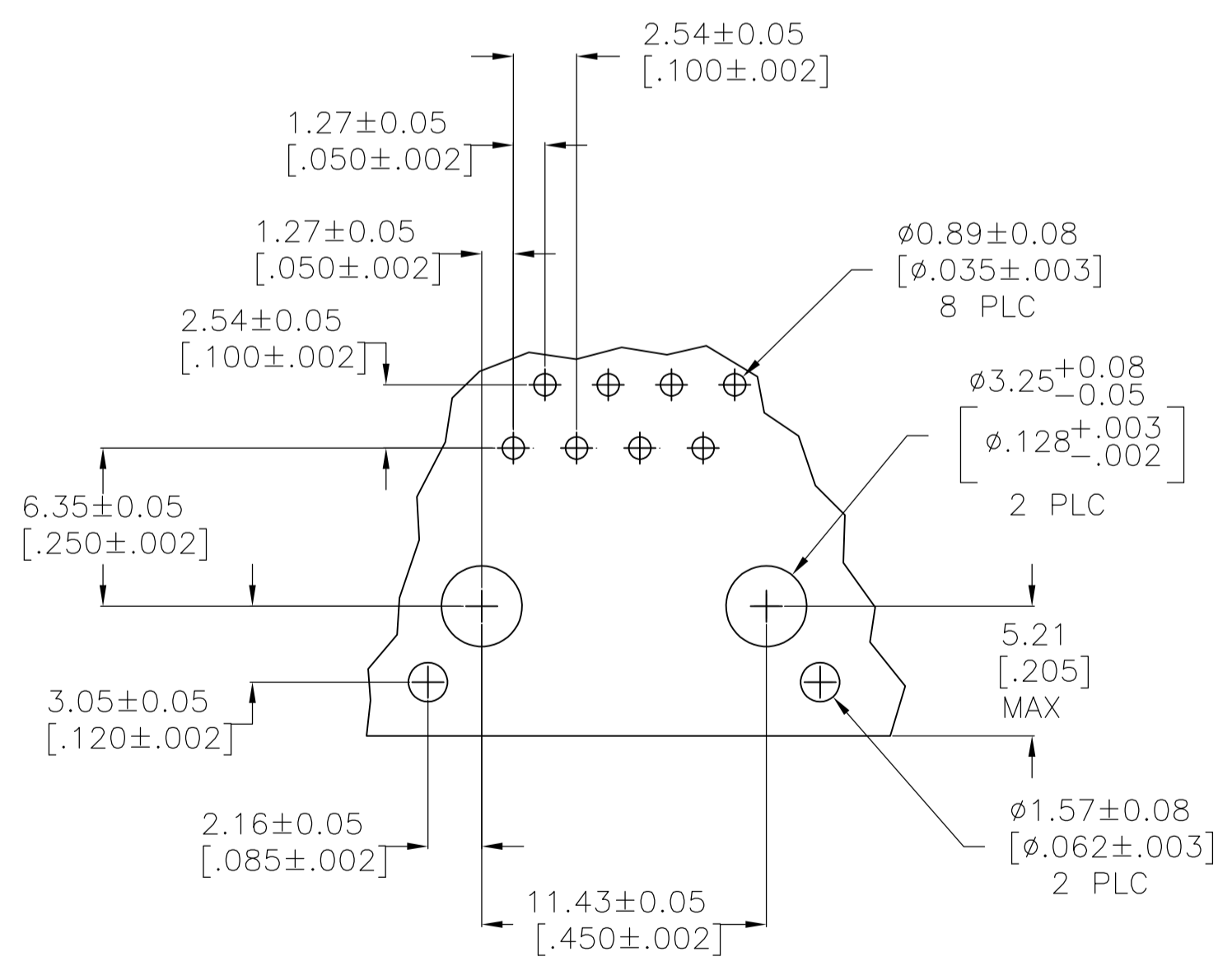


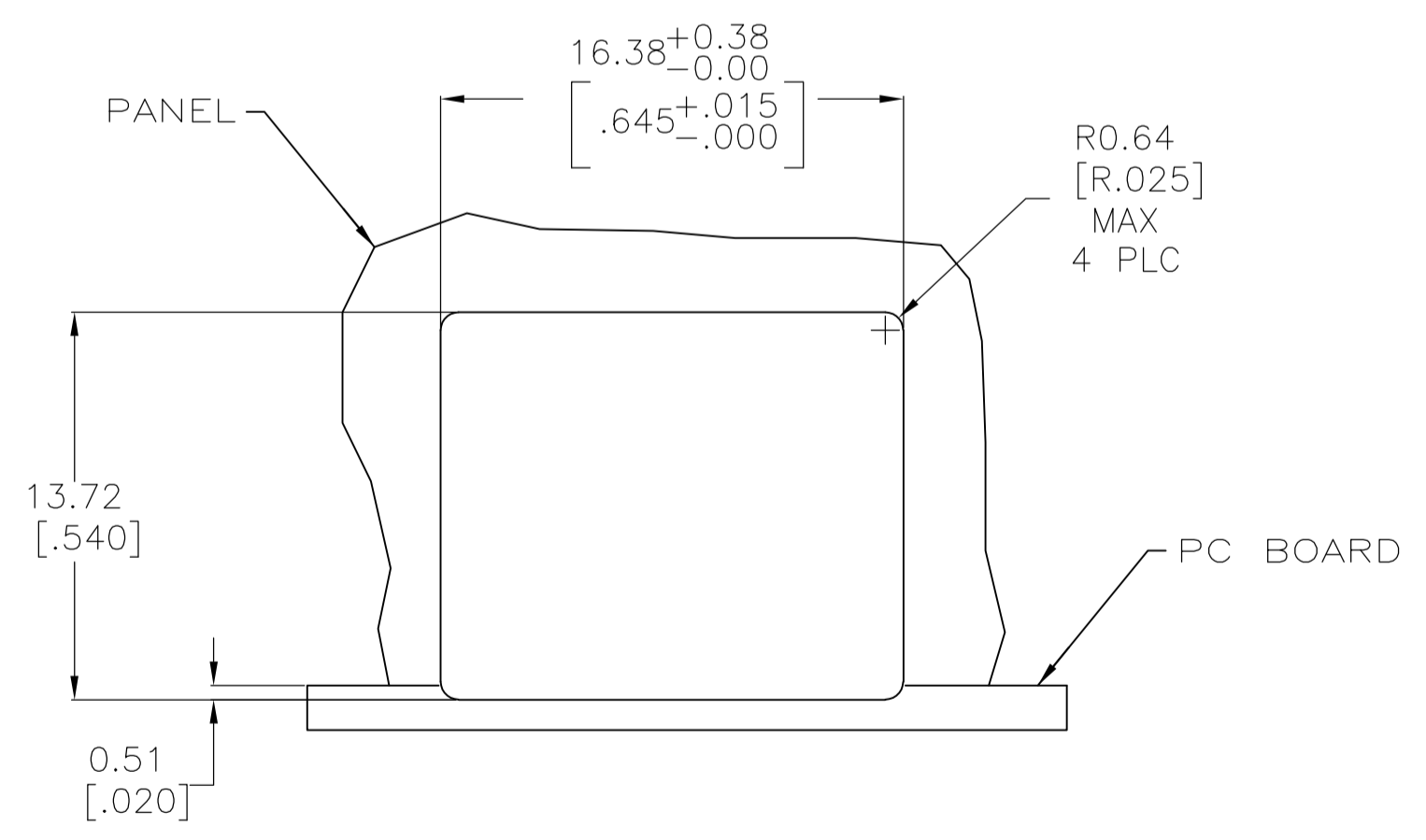
REVISIONS					
P	LTR	DESCRIPTION	DATE	DMN	APVD
D2		REVISE PER ECO-16-008229	31MAY2016	AD	SH



DETAIL B
SCALE 2:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

- MATERIAL:
HOUSING - PBT POLYESTER, COLOR: BLACK
TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03 μ m [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m [.000050] THICK NICKEL UNDERPLATE
SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m [.000120] MINIMUM THICK REFLOWED TIN
- △2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - △3 DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE
 - △4 BULK PACKAGED IN A TRAY
 - △5 32 ASSEMBLIES PACKAGED PER TUBE. SEE DETAIL B
 - △6 MATERIAL OF HOUSING: HIGH TEMPERATURE THERMOPLASTIC. COLOR: BLACK

3.30-4.32 [.15±.02]	△4	1-5555153-1
1.78-2.79 [.09±.02]	△4	5555153-6
2.54-3.05 [.11±.01]	△4	5555153-5
3.30-4.32 [.15±.02]	△5	5555153-3
3.30-4.32 [.15±.02]	△4	5555153-1
DIM A	PACKAGED	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G GARRETT/L.A. MAYER 05NOV2007		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CIR P RECCE 05NOV2007		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S FLICKINGER 05NOV2007		PRODUCT SPEC	
0 PLC ± -		APPLICATION SPEC		MODULAR JACK ASSEMBLY, LOW PROFILE, PANEL GROUND WITH PANEL STOPS	
1 PLC ± -		114-2048		108-1163	
2 PLC ± 0.13[.005]		WEIGHT 0.000000		114-2048	
3 PLC ± -		CUSTOMER DRAWING		114-2048	
4 PLC ± -		SCALE 4:1		SHEET 1 OF 1	
ANGLES ± -		RESTRICTED TO		REV D2	